

## Bill of Materials

TI DESIGNS

TIDA-00332

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	2	C1, C2	10pF	CAP, CERM, 10pF, 50V, +/-5%,	Kemet	C0603C100J5GACTU	CL10C100JB8NCNC	0603	
2	1	D1	12V	Diode, Zener, 12V, 500mW, SOD- 323	Diodes Inc.	DDZ12CSF-7	MM3Z12VST1G	SOD-323	
3	5	GND, GND_1, TP3 Out, TP1 400V, TP2 390V	SMT	Test Point, Compact, SMT	Keystone	5016			
4	2	J1 Vin, J3 Vout	10A	Standard Banana Jack, insulated, 10A, red	DEM Manufacturing	571-0500			
5	2	J2 GND, J4 GND	10A	Standard Banana Jack, insulated, 10A, black	DEM Manufacturing	571-0100			
6	1	Q2	500V	Transistor, PNP, 500V, 0.5A, SOT- 23	ST	STR2550	PBHV9050T,215	SOT-23	
7	1	R1	200k	RES, 200kohm, 1%, 1W, 2010	Vishay-Dale	CRCW20101R00JNEFHP	CRM2010-FX-2003ELF	2010	
8	1	R2	0.05	RES, 0.05 ohm, 1%, 2W, 2512	Stackpole Electronics Inc	CSRN2512FK50L0	PF2512FKF7W0R05L	2512	
9	1	R3	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	Rohm Semiconductor	MCR03ERTF4992	RC1608F4992CS	0603	
10	1	U3	INA138	IC, High-Side Measurement Current Shunt Monitor	TI	INA138	INA139	SOT23	

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